

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20370

Generic Copy

Issue Date: 22-Jan-2014

<u>TITLE</u>: Final Notification for Qualification of CM1213A-04S7 in ON Semiconductor Pocatello (wafer fab) and LPS China (assembly & test site).

PROPOSED FIRST SHIP DATE: 22-Apr-2014

AFFECTED CHANGE CATEGORY(S): Die layout, date code marking, wafer fab site, assembly & test site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <<u>SueiHuey.Wong@onsemi.com</u>>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or < laura.rivers@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

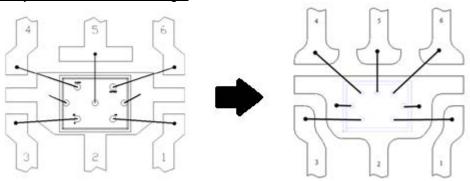
Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is the final notification announcing that for CM1213A-04S7, the wafer fab will be transferred to ON Semiconductor Pocatello in Idaho, USA and the assembly & test site will be transferred to Leshan-Phoenix Semiconductor in Leshan, China. Both sites are ON Semiconductor's internal factories and both are certified for ISO/TS 16949. These products will continue to meet RoHS requirements and are also Halide Free.

Die layout and leadframe change:

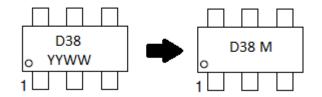


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Date code marking change:



D38: device marking

M: one digit month code based on table below.

ODD YEARS EVEN YEARS

(example: 2007/2009/2011, etc) (example: 2006/2008/2010, etc)

ODD Years	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
	1	2	3	4	5	6	7	8	9	Т	V	O
EVEN Years	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
	Е	F	Н	J	K	L	N	Р	U	Х	Υ	Z

RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Interval	Results
HTRB+PC	TA=125C,80% Rated Voltage	1008 hrs	0/234
IOL+PC	Ta=25C, delta Tj=100C, On/off=2mis	1008 hrs	0/234
TC+PC	Ta= -65 C to 150 C	1000 cyc	0/234
AC+PC	Ta=121C RH=100% ~15 psig	96 hrs	0/234
HAST+PC	Ta=130C RH=85% ~18.8 psig	96 hrs	0/234
RSH	Ta=260C, 10 sec dwell		0/90

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request.

CHANGED PART IDENTIFICATION:

Finished goods with date code marking of J (April 2014) or later may be sourced from new wafer fab in Pocatello and assembly & test site in LPS.

List of affected General Parts:

CM1213A-04S7

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